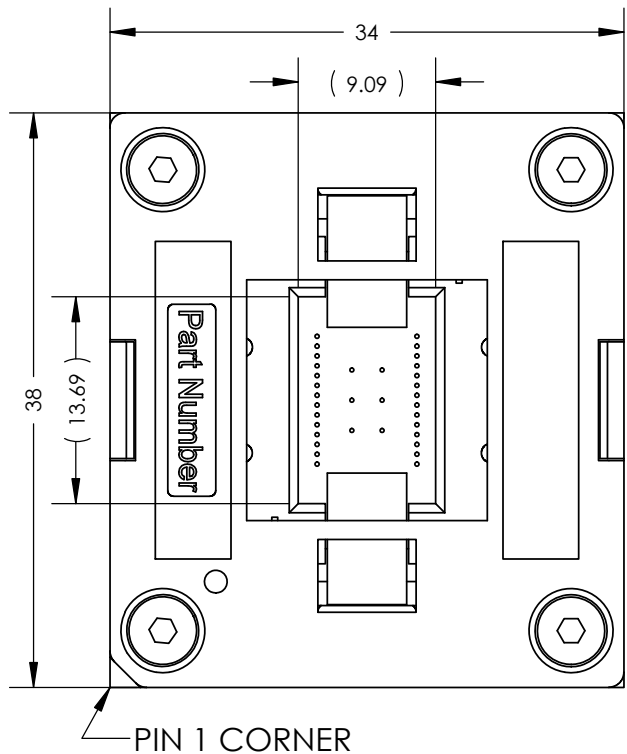
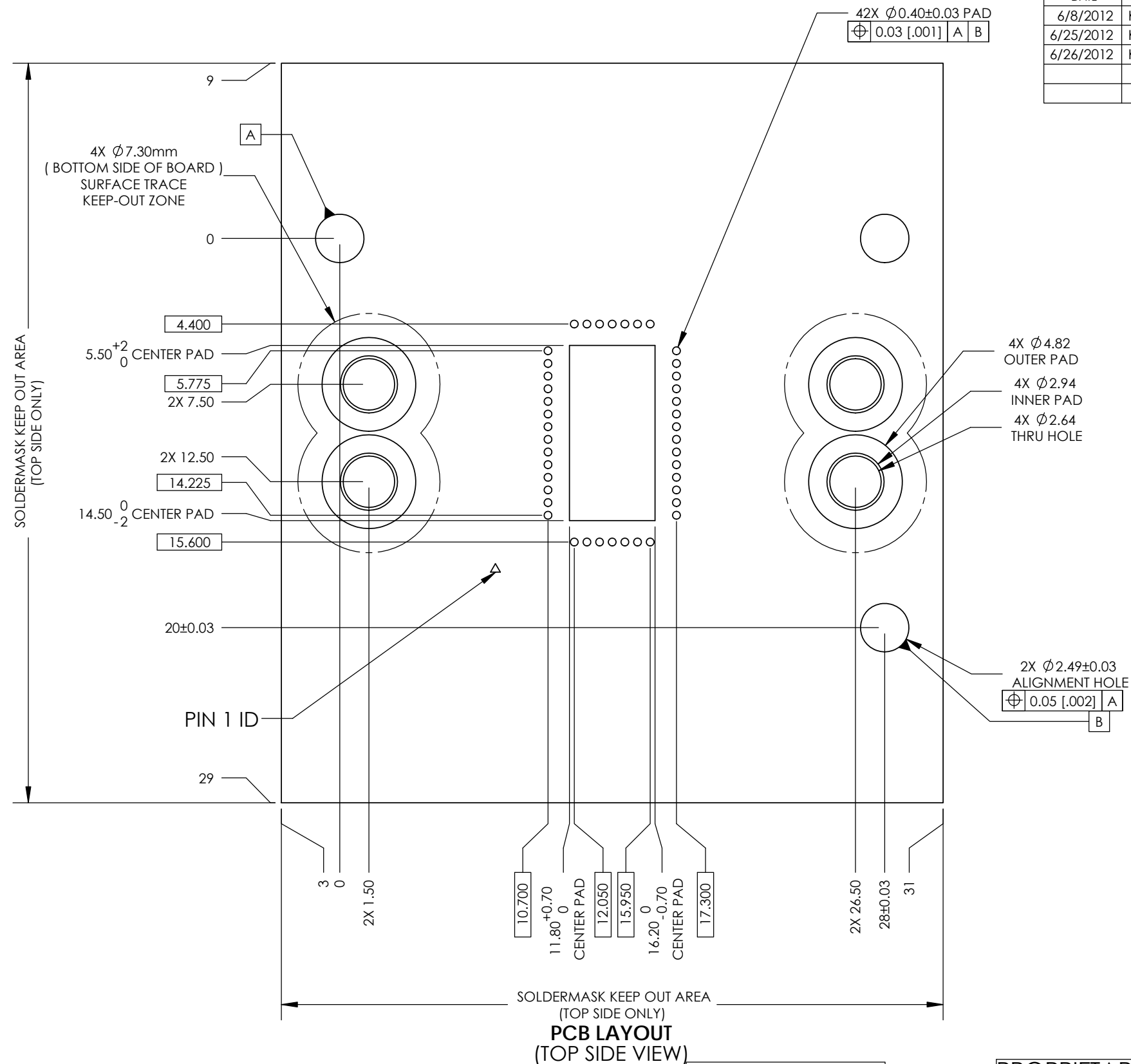
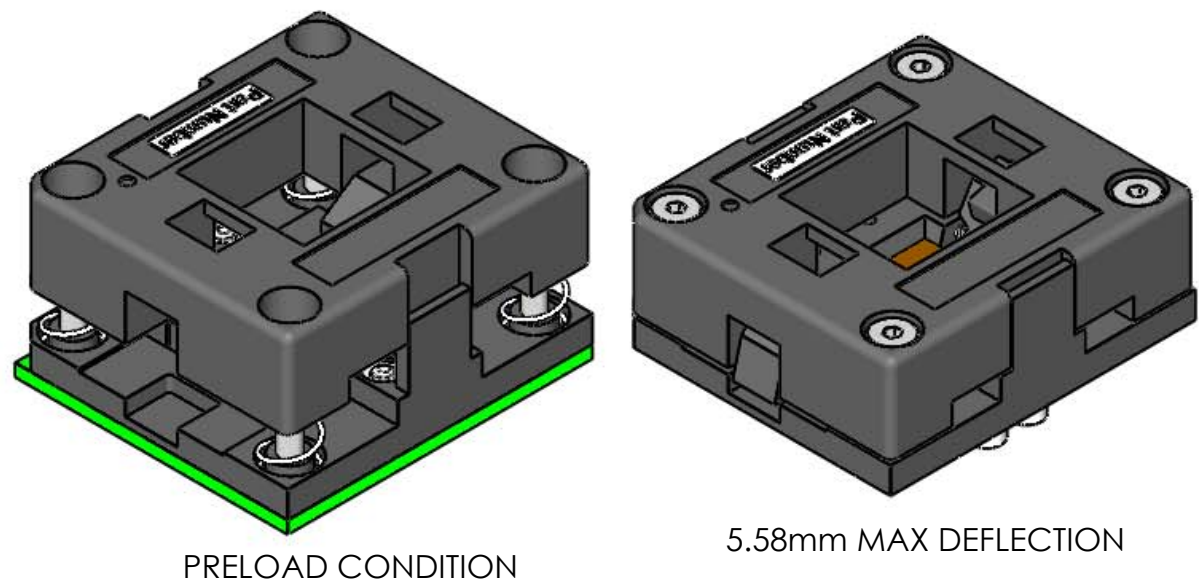


DATE	DRN
6/8/2012	KDS
6/25/2012	KDS
6/26/2012	KDS



NOTES:

1. PCB PAD PLATING: 30  $\mu$ m. HARD Au OVER 300  $\mu$ m. Ni OVER 1oz. MIN. Cu
2. ALL Au PADS SHOULD BE SAME THICKNESS
3. PCB LAYOUT TOLERANCE:  $\pm$  0.05mm
4. CLOSING FORCE IS 4.8 LB. OVER 5.58mm TRAVEL
5. PCB HARDWARE: #2-56
6. TOOLS REQUIRED FOR ASSEMBLY: 5/64" ALLEN TORQUE DRIVER
7. CONTACT PLATING: 30  $\mu$ m. Au OVER 75  $\mu$ m. Ni
8. CONTACT FORCE: 26gF
9. CONTACT RESISTANCE: < 30 m $\Omega$
10. NO FILLED VIAS. VIAS MUST BE OFFSET.
11. FORCE PER LATCH IS 1.20lbf., PRESSURE ON PACKAGE PER LATCH IS 325 PSI.



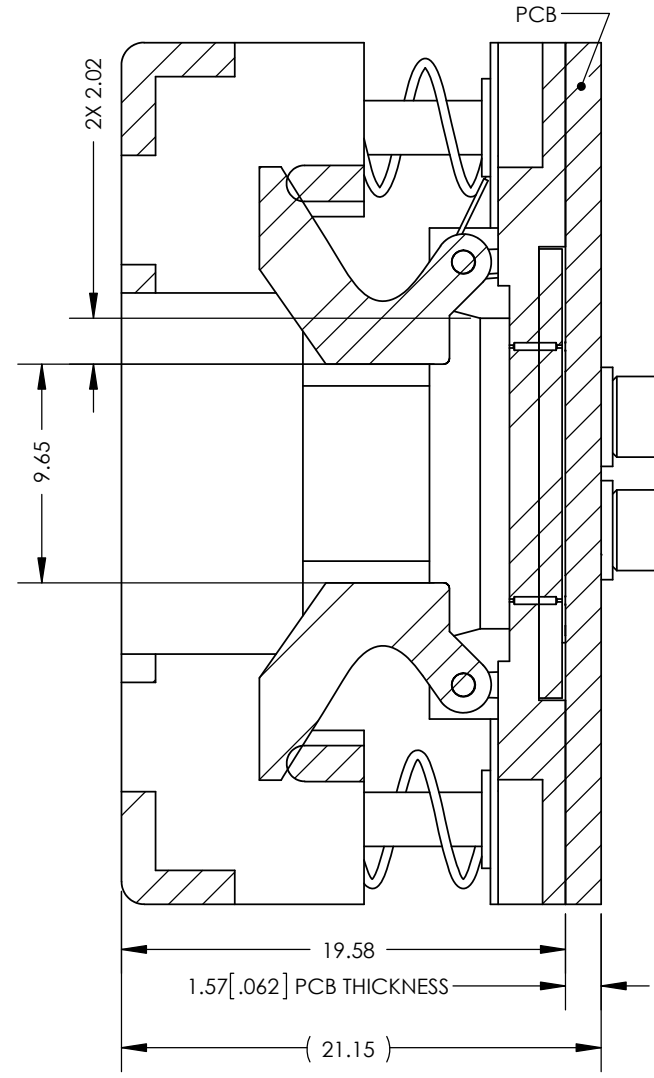
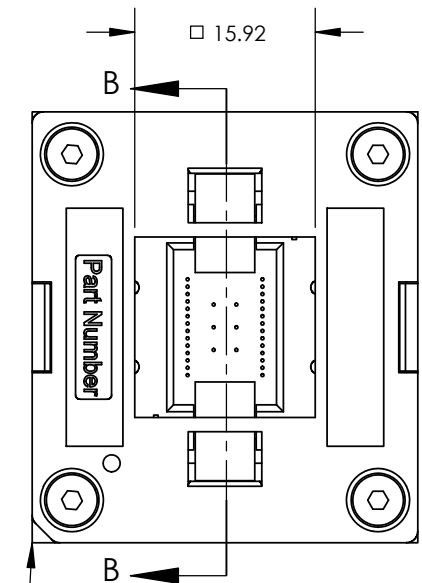
PCB LAYOUT (TOP SIDE VIEW)

P/N: 42QHRAS65Y01

PROPRIETARY

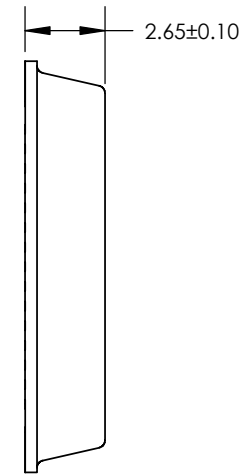
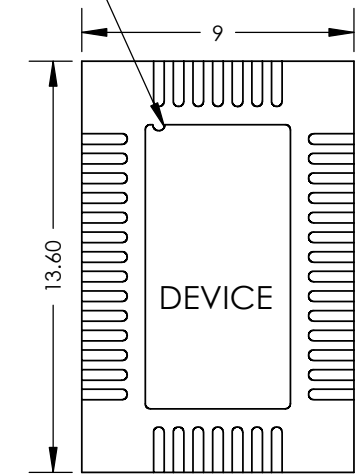
- FEATURES:
1. PIN: H038LL2A
  2. 6 CENTER PINS
  3. DEVICE THICKNESS: ( 2.65 )
  4. 2 SPRING LOADED SIDE LATCHES
  5. STEEP NEST LEAD-IN / NO LID LEAD-IN

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME	DATE	DWG NO. S42QHRAS65Y01	SHEET 1 OF 2
	DRAWN	KDS	6/8/2012	TITLE: H-PIN LGA OT, 13.6 x 9.0mm DEVICE, 0.65mm PITCH, 42x H-PINS	
SCALE: VARIOUS	CHECKED				
UNITS: mmgs	ENG APPR.				
SOLIDWORKS CREATED FILE	MFG APPR.				



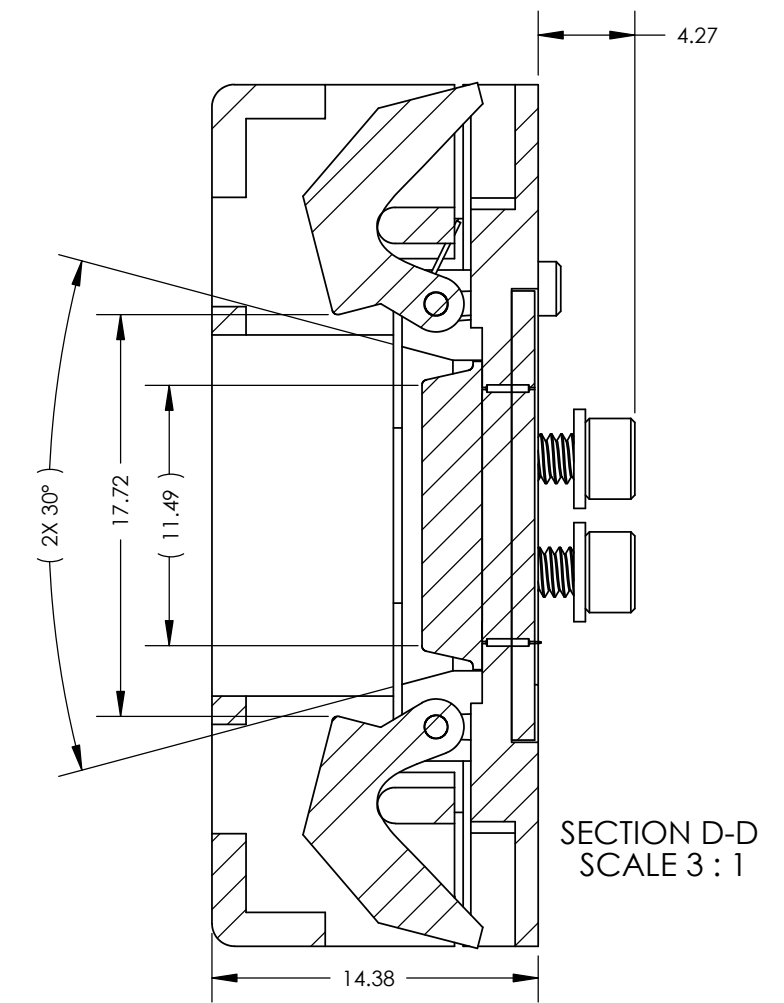
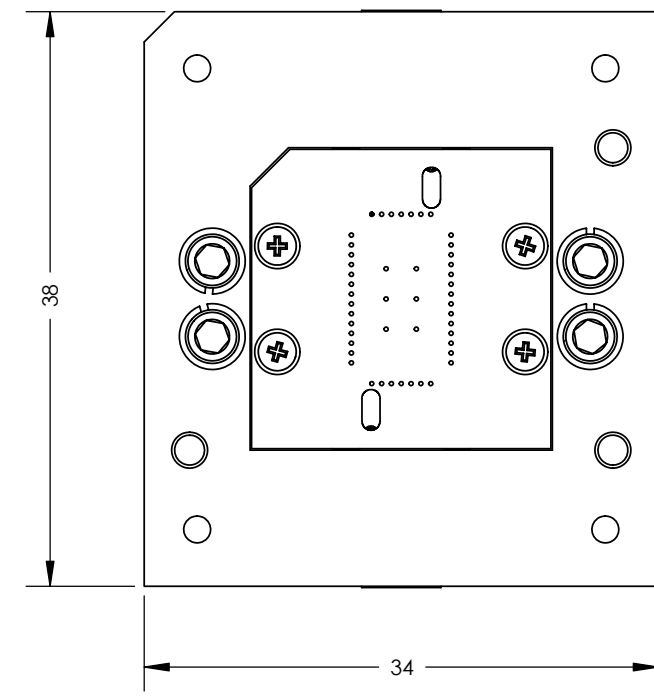
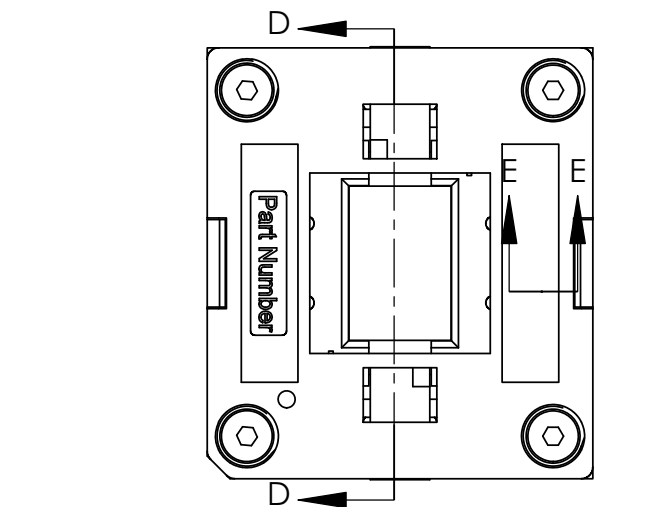
SECTION B-B  
SCALE 3 : 1

PIN 1 CORNER

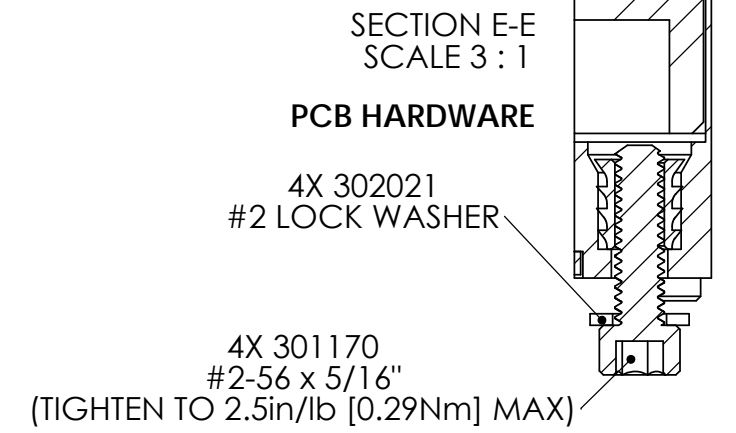


PRELOAD  
CONDITION

5.58mm MAX  
DEFLECTION



SECTION D-D  
SCALE 3 : 1



SECTION E-E  
SCALE 3 : 1

PCB HARDWARE

4X 302021  
#2 LOCK WASHER

4X 301170  
#2-56 x 5/16"  
(TIGHTEN TO 2.5in/lb [0.29Nm] MAX)

P/N: 42QHRAS65Y01

PROPRIETARY

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.	SIZE: B	NAME	DATE	DWG NO. S42QHRAS65Y01	SHEET 2 OF 2
	DRAWN	KDS	6/8/2012	TITLE: H-PIN LGA OT, 13.6 x 9.0mm DEVICE, 0.65mm PITCH, 42x H-PINS	
	SCALE: VARIOUS	CHECKED			
	UNITS: mmgs	ENG APPR.			
SOLIDWORKS CREATED FILE	MFG APPR.				